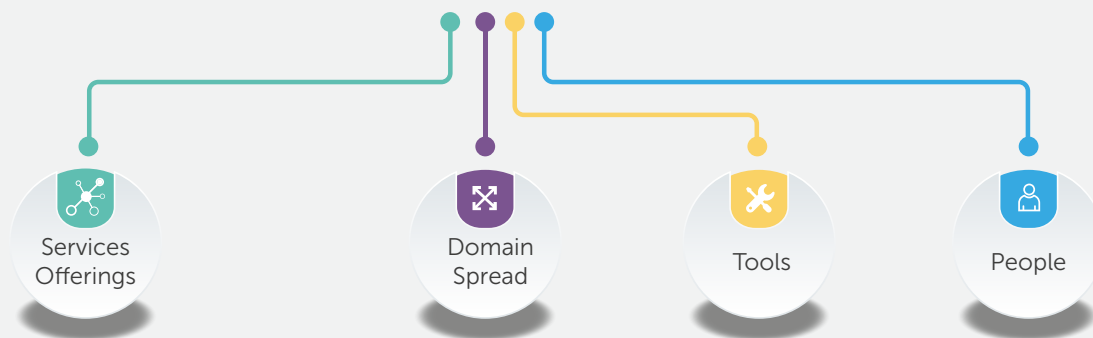


# Engineering Analysis Practice



### Structural Analysis

- Linear, Non linear & Contact analysis
- Low and High Cycle Fatigue analysis
- Vibration Analysis
- Modal Analysis
- Frequency Response Analysis
- Random Response Analysis
- Shock Spectrum Analysis
- Vibro - Acoustic Analysis
- Drop Simulation
- Kinematics Simulation

### CAE Analysis

- Conjugate heat Compressible and incompressible flow
- Steady and transient transfer analysis
- Fluid structure interaction
- Thermal design and analysis of electronic systems
- PCB layout optimization

- Consumer Electronics / Appliances
- Automotive & Heavy Engineering
- Aerospace
- Hi-tech & Manufacturing
- Medical Devices

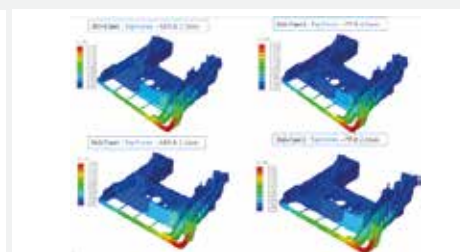
- ANSYS, MSC. Nastran, ABAQUS, LS-DYNA, IDEAS, Pro/MECHANICA, MSC. Adams, LMS Synoise, Hyper Mesh, FLUENT, CFX, ICEM-CFD, Icepak, Flotherm, CF-Design, Moldflow

- 200+ Analysts (Structural-150; CFD-35 & Electronic Packaging - 15)
- Average Experience: Principle Analyst 15+ years; Senior Analyst 8+ years; and team members with 4+ years
- Qualifications: Masters - 85%, Bachelors - 15%;

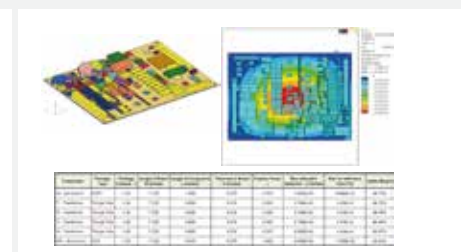
## CAE - PROOF POINTS



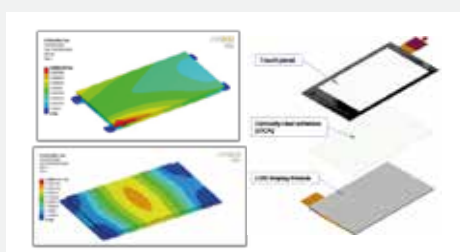
Thermal imaging camera - Drop/impact test



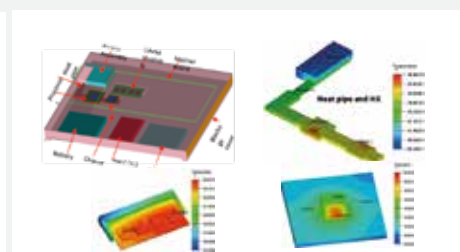
Vacuum cleaner foot - Non Linear Analysis



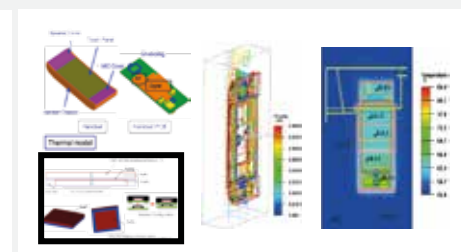
Vibration studies on electronic components



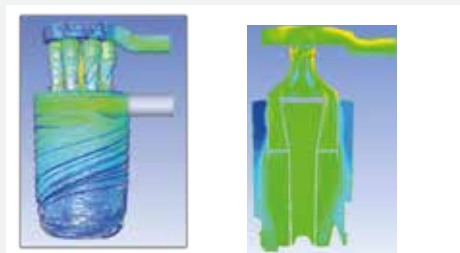
Cohesive zone modeling - De-bonding analysis



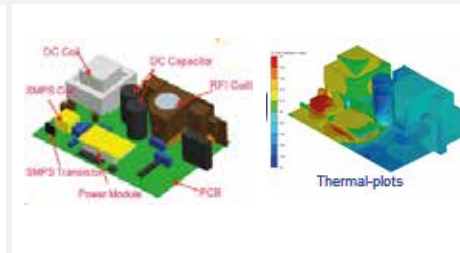
Laptop: Thermal Design



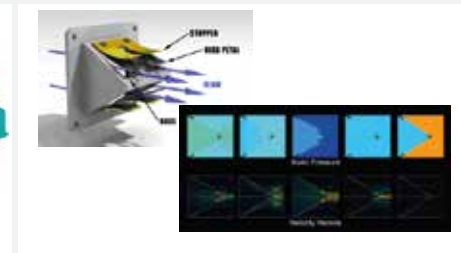
Android Handset - Thermal Design



Cyclone Separator - Multiphase fluid flow



PSU Heatsink Optimization - Thermal design



Reed Valve - Fluid Structure Interaction Analysis